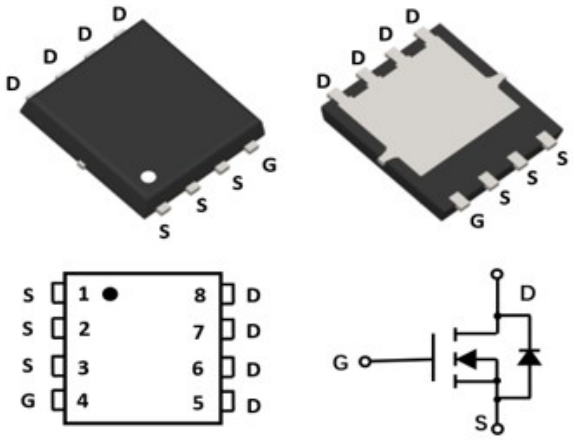
RoHS COMPLIANT

N-Channel Enhancement Mode Field Effect Transistor

PDFN 5X6



Product Summary

- V_{DS} 60V
- I_D 30A
- $R_{DS(ON)}$(at V_{GS}= 10V) ＜20mohm
- $R_{DS(ON)}$(at V_{GS}= 4.5V) ＜23mohm

General Description

- Trench Power MV MOSFET technology
- High density cell design for Low $R_{DS(ON)}$
- High Speed switching

Applications

- DC-DC Converters
- Power management functions
- Backlighting

■ Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	60	V
Gate-source Voltage		V_{GS}	±20	V
Drain Current	T_C=25℃	I_D	30	A
	T_C=100℃		19	
Pulsed Drain Current [A]		I_{DM}	130	A
Total Power Dissipation @ T_C=25℃		P_D	30	W
Single Pulse Avalanche Energy [B]		E_{AS}	100	mJ
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	5	℃/ W
Junction and Storage Temperature Range		T_J ,T_{STG}	-55～+150	℃

■ Ordering Information (Example)

PREFERED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG30N06A	F1	YJG30N06A	5000	10000	100000	13“ reel

■ Electrical Characteristics (T_J=25℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}= 0V, I_D=250μA	60			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=60V,V_{GS}=0V			1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}= ±20V, V_{DS}=0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}= V_{GS}, I_D=250μA	1.0	1.5	2.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	V_{GS}= 10V, I_D=15A		16	20	mΩ
		V_{GS}= 4.5V, I_D=10A		17.5	23	
Diode Forward Voltage	V_{SD}	I_S=10A,V_{GS}=0V		0.85	1.2	V
Maximum Body-Diode Continuous Current	I_S				30	A
Dynamic Parameters						
Input Capacitance	C_{iss}	V_{DS}=30V,V_{GS}=0V,f=1MHZ		2027		pF
Output Capacitance	C_{oss}			132		
Reverse Transfer Capacitance	C_{rss}			116		
Switching Parameters						
Total Gate Charge	Q_g	V_{GS}=10V,V_{DS}=30V,I_D=10A		51		nC
Gate-Source Charge	Q_{gs}			8.1		
Gate-Drain Charge	Q_{gd}			11.4		
Reverse Recovery Charge	Q_{rr}	I_F=20A, di/dt=500A/us		11.4		
Reverse Recovery Time	t_{rr}			22		ns
Turn-on Delay Time	$t_{D(on)}$	V_{GS}=10V, V_{DD}=30V, I_D=2A, R_{GEN}=3Ω		11		
Turn-on Rise Time	t_r			21		
Turn-off Delay Time	$t_{D(off)}$			40		
Turn-off fall Time	t_f			23		

A. Pulse Test: Pulse Width≤300us,Duty cycle ≤2%.

B. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.

■ Typical Performance Characteristics

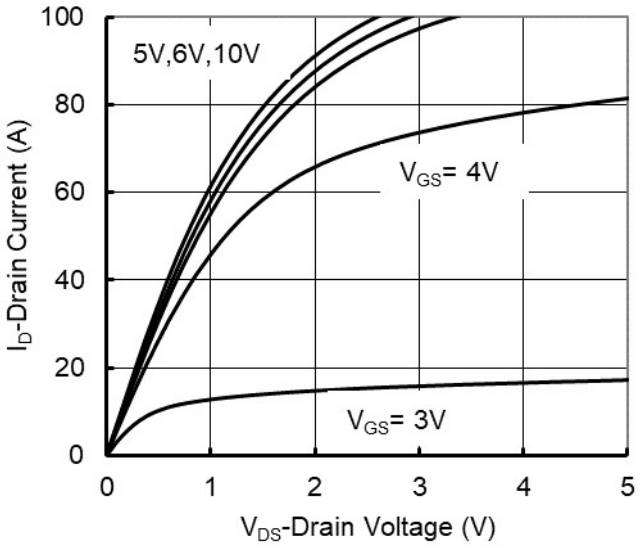


Figure 1. Output Characteristics

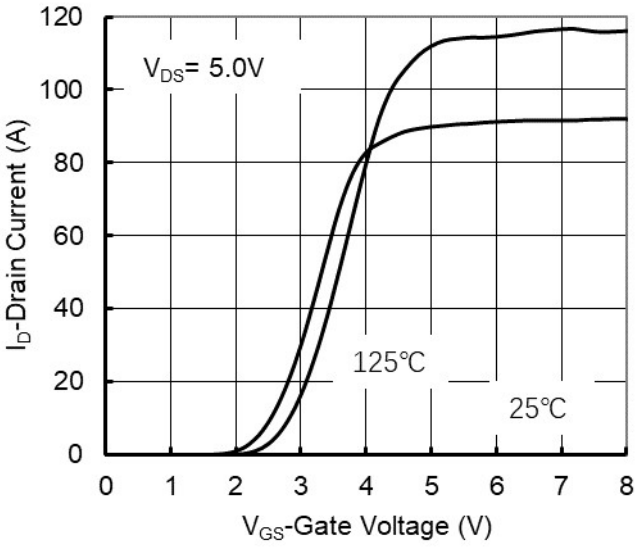


Figure 2. Transfer Characteristics

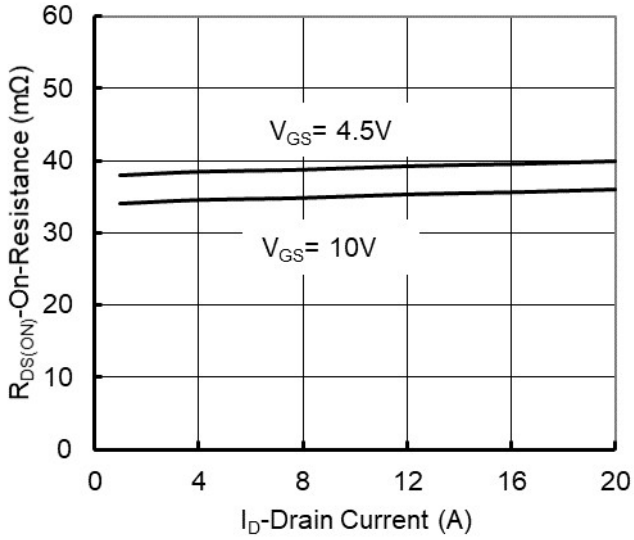


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

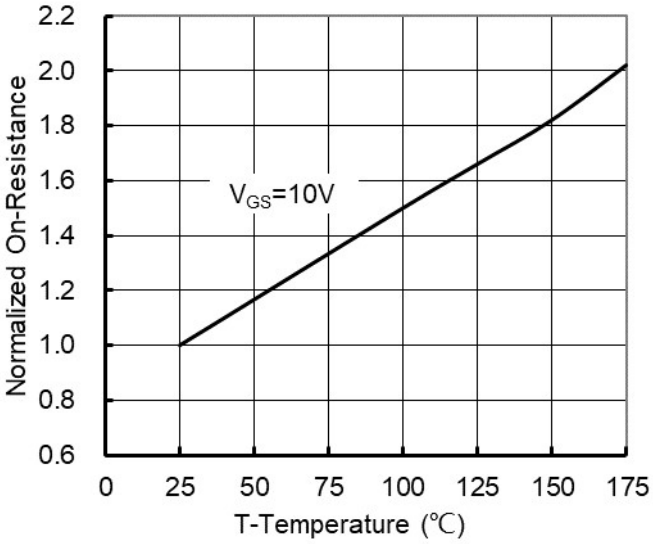


Figure 4. On-Resistance vs. Junction Temperature

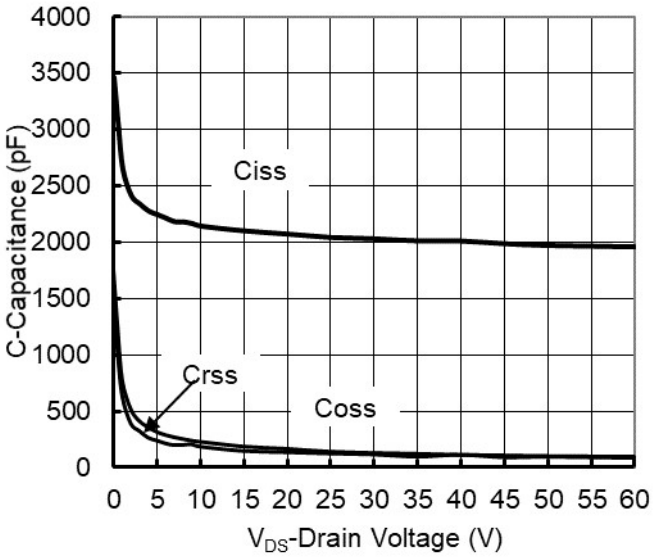


Figure 5. Capacitance Characteristics

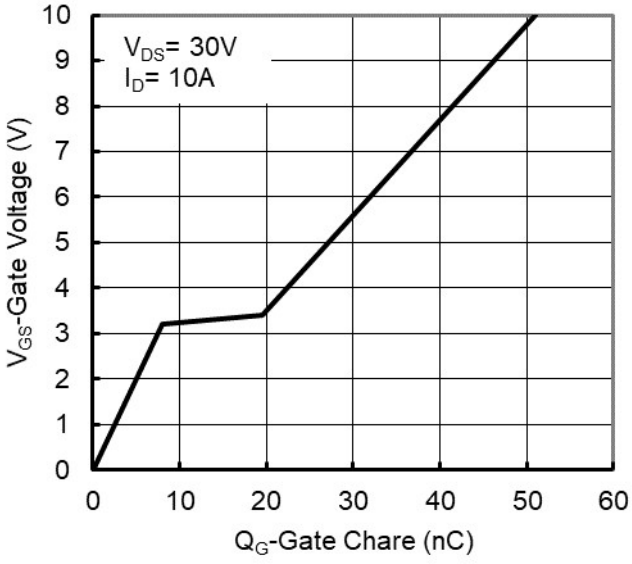


Figure 6. Gate Charge

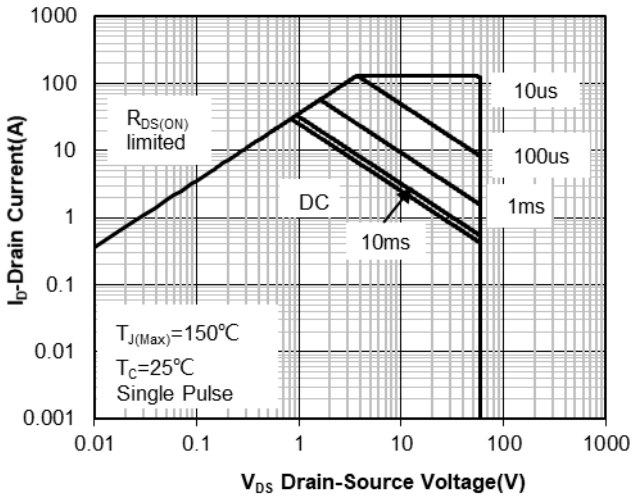


Figure 7. Safe Operation Area

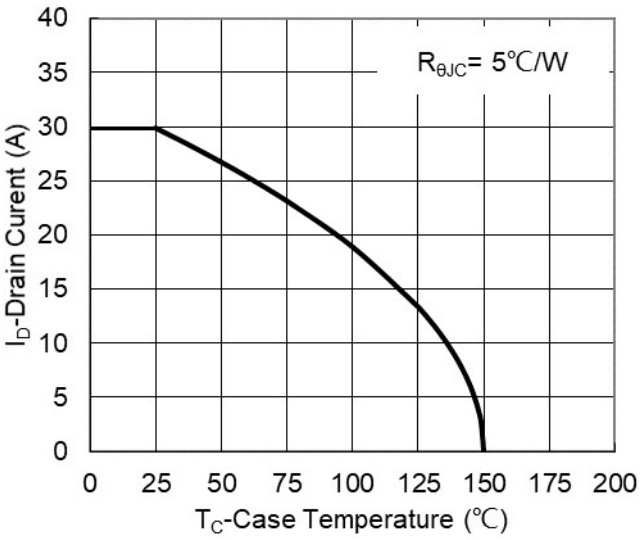


Figure 8. Maximum Continuous Drain Current vs Case Temperature

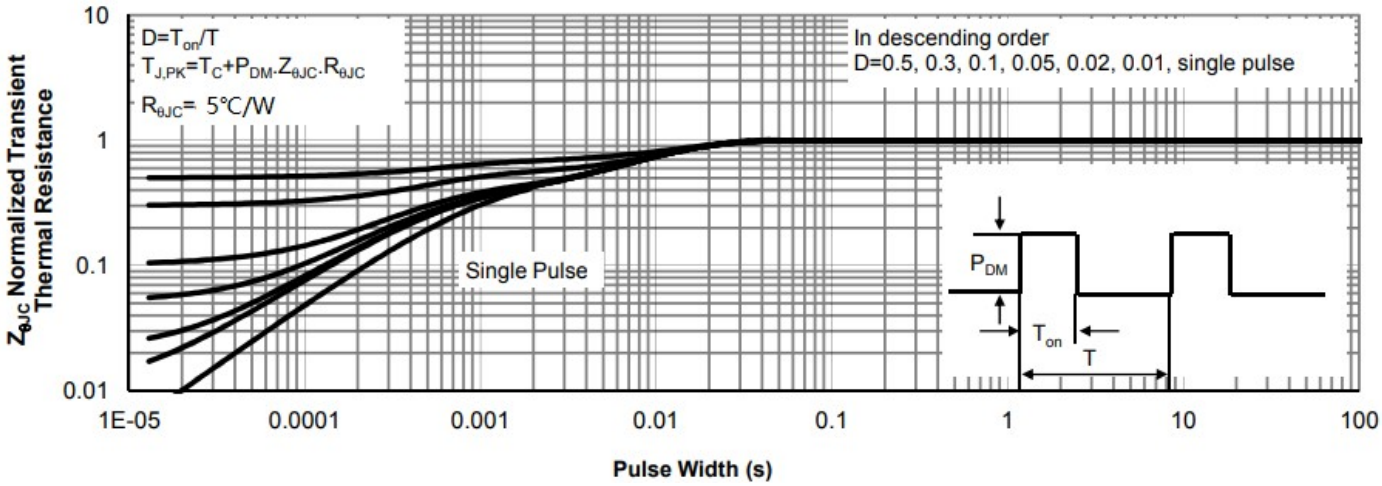
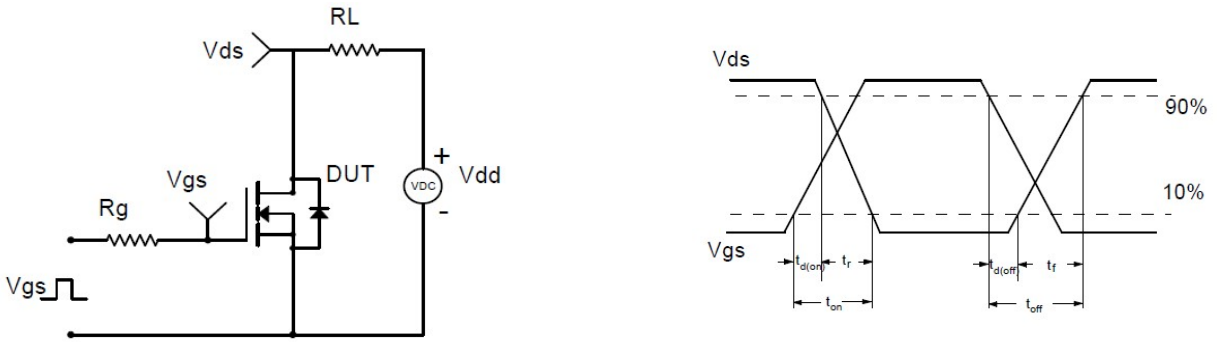
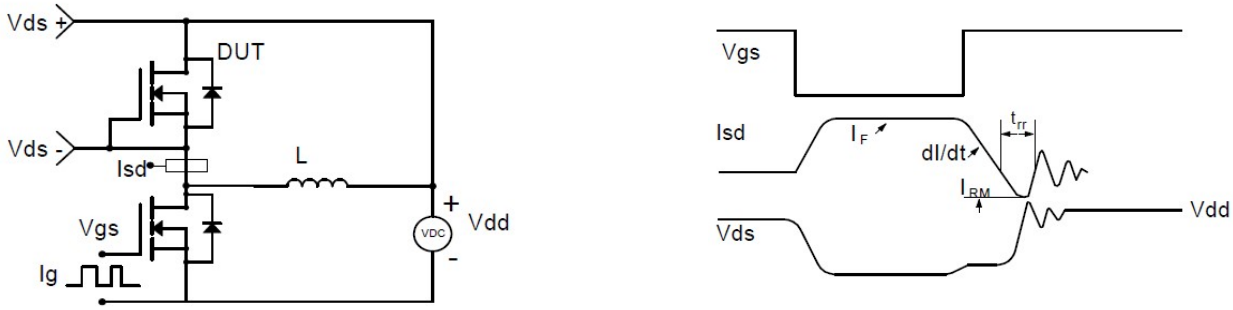


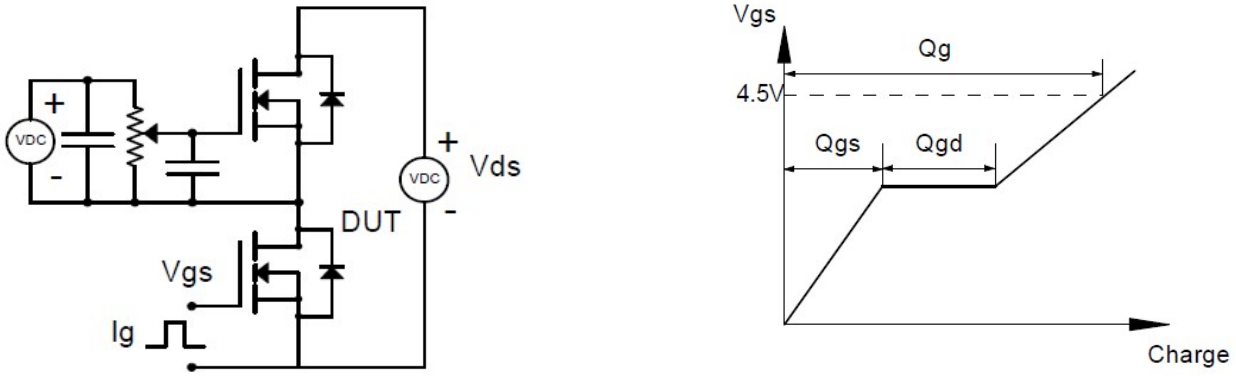
Figure 9. Normalized Maximum Transient Thermal Impedance



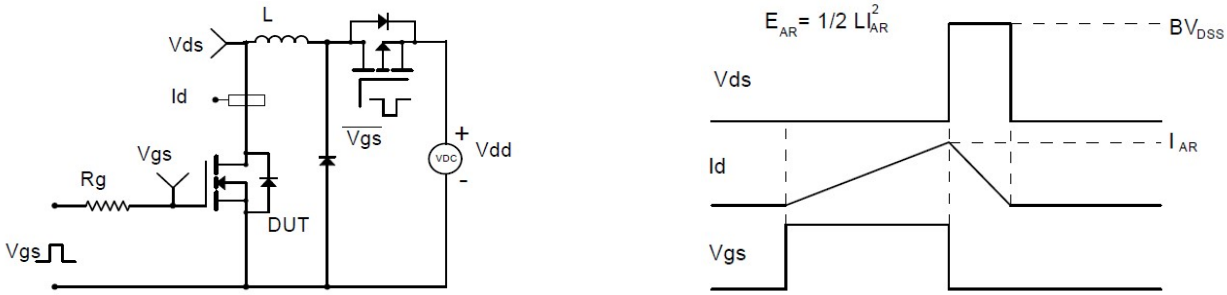
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

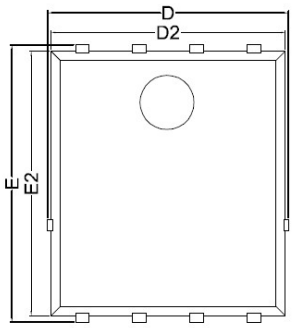


Gate Charge Test Circuit & Waveform

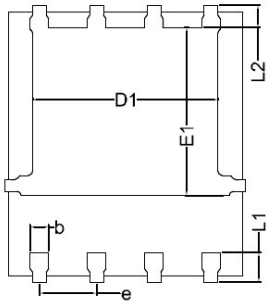


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

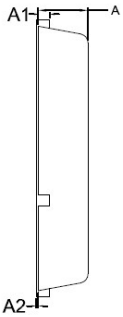
■PDFN5X6 Package information



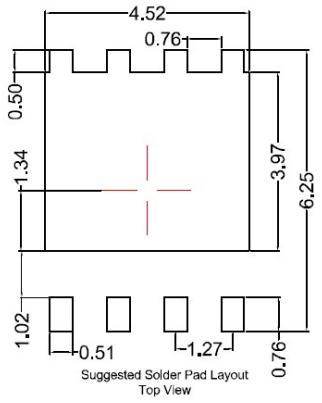
Top View
正面视图



Bottom View
背面视图



Side View
侧面视图



Suggested Solder Pad Layout
Top View

Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.10mm.
3.The pad layout is for reference purposes only.

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1		0.254 BSC	
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
L1	0.56	0.66	0.76
L2		0.50 BSC	
b	0.31	0.41	0.51
e		1.27 BSC	

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